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REMARKS

Reconsideration of this application is respectfully requested in view of the foregoing amendment and the following remarks.

By the foregoing amendment, claims 1, 3 and 11 have been amended. Thus, claims 1, 3-5, and 11 remain pending.

In the Office Action, the Examiner rejects claims 1 and 3-5 under Section 112. To overcoming this rejection, applicants have revised the claims to use the term "non-cut" instead of "initial" while replacing the term "cut" for "final", as per amended claim 1 attached here. This amendment is supported by the description extending from page 21, line 22 to page 23, line 21, where the cutting or dividing operation for the resin packages is explained and where the package 4a after the cutting is referred to as "cut resin package" (Page 23, line 21). It is believed apparent that the package before the cutting can be referred to as a "non-cut package".

In addition, claim 11 has been amended to correct an obvious error. In the last paragraph of former claim 11, the "dummy pattern" was defined to be formed on the "obverse surface" of the substrate, which is contradictory to the disclosed embodiment. Such a dummy pattern should indeed be formed on the reverse surface of the substrate in corresponding position and configuration to the wiring pattern on the obverse surface of the substrate, as

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defined in amended claim 11 and as set forth in original claim 8 held allowable by the Examiner in the first Office Action.

In fact, former claim 11 was prepared as an independent claim corresponding in scope to original claim 8, but the applicant attempted to make editorial revisions for converting the method-like product claim (combination of original claims 6-8) into a more product-like claim. This attempt resulted in the above-noted obvious error. The true applicant's intention may be clear to the Examiner from the fact that original claim 8, though held to be allowable, was deleted in favor of former claim 11 in the previous Amendment of September 13, 2002.

For this reason, though the pending Office Action is final, the Examiner is respectfully requested to enter and consider amended claim 11, which virtually corresponds to original claim 8 previously held allowable because it does not raise any new issue.

As noted by the Examiner, U.S. Patent No. 5,677,575 to Maeta et al merely shows a dummy pattern 7c formed on the obverse surface of a substrate 7. Further, the dummy pattern does not correspond in position and configuration to the wiring pattern 7a.

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In view of the foregoing all of the claims in this case are believed to be in condition for allowance. Should the Examiner have any questions or determine that any further action is desirable to place this application in even better condition for issue, the Examiner is encouraged to telephone applicants' undersigned representative at the number listed below.

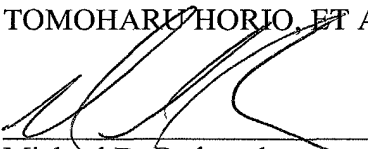
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Respectfully submitted,

TOMOHARU HORIO, ET AL.

Date: February 21, 2003

By:


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Attachments: Amended Claims w/ Markings

MDB/lrhj

Customer No. 28970

VERSION WITH MARKINGS TO SHOW CHANGES MADE TO CLAIMS

1. (Twice Amended) A method of making infrared data communication modules comprising the steps of:

forming predetermined conductor patterns on an obverse and a reverse surfaces of a substrate;

mounting, on one of the surfaces of the substrate, plural sets of light emitting elements and light receiving elements;

resin-molding [an initial] a non-cut package which encloses the plural sets of light emitting elements and light receiving elements on the substrate; and

dividing the [initial] non-cut package into a plurality of [final] cut packages each of which encloses a respective set of light emitting element and light receiving element;

wherein the mounting step includes arranging the plural sets of light emitting elements and light receiving elements in a matrix on said one surface of the substrate; and

wherein the resin-molding step includes forming a plurality of [initial] non-cut packages arranged in a matrix.

3. (Twice Amended) The method of making infrared data communication modules according to claim [2] 1, wherein the substrate is elongated in one direction, the substrate being formed with a plurality of slits extending widthwise of the substrate and spaced from each other longitudinally of the substrate, the plural sets of light emitting elements and light receiving elements being mounted on said one surface of the substrate in each of regions defined between the slits.

11. (Amended) An infrared data communication module comprising:
a substrate having an obverse surface and a reverse surface,
a wiring pattern formed on the obverse surface of the substrate,
a set of light emitting element and light receiving element mounted on the obverse surface of the substrate in electrical connection to the wiring pattern,
a resin package formed on the obverse surface of the substrate for enclosing the set of light emitting element and light receiving element,
a plurality of terminals formed on the reverse surface of the substrate in electrical connection to the wiring pattern, and
a dummy pattern formed on the [obverse] reverse surface of the substrate but electrically separated from the wiring pattern and the terminals, the dummy pattern corresponding in position and in general configuration to the wiring pattern.